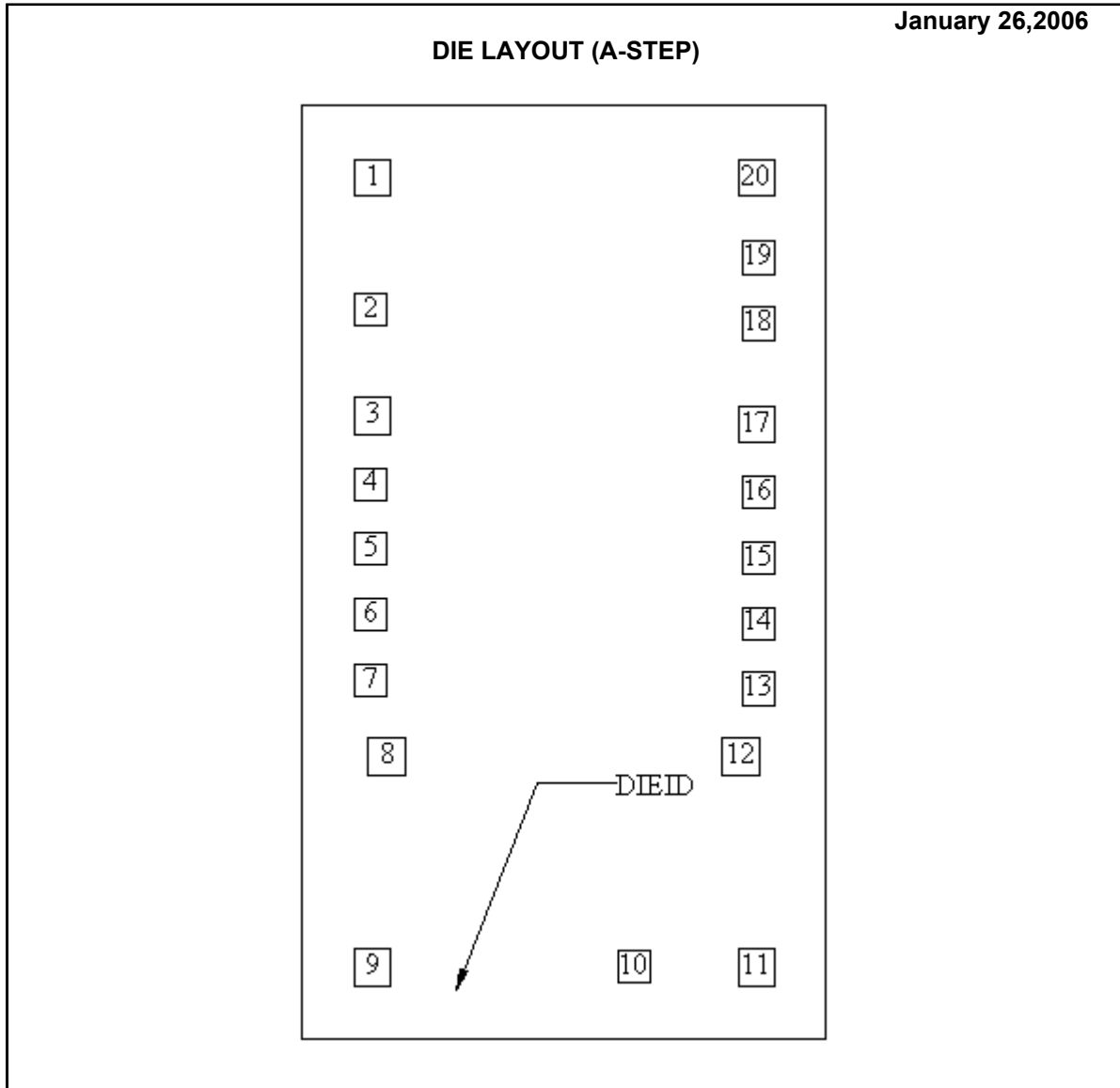


LM56C MDC MWC
DUAL OUTPUT LOW POWER THERMOSTAT



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LM56A	Bond Pad Opening Size (min)	91µm x 91µm
Die Step	A	Bond Pad Metalization	0.5% COPPER_BAL. ALUMINUM
Physical Attributes		Passivation	PECVDOX+NITRIDE
Wafer Diameter	150mm	Back Side Metal	BARE BACK
Die Size (Drawn)	1295µm x 2311µm 51.0mils x 91.0mils	Back Side Connection	GND
Thickness	406µm Nominal		
Min Pitch	521µm Nominal		

Special Assembly Requirements:
Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (A -Step)						
(Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used						
SIGNAL	PAD#	XY COORDINATES		PAD SIZE		
NAME	NUMBER	X	Y	X	Y	
VREF	1	-475	976	91	x	91
NC	2	-478	650	79	x	80
VT2	3	-475	388	91	x	91
NC	4	-478	219	79	x	80
NC	5	-478	57	79	x	80
NC	6	-478	-105	79	x	80
NC	7	-478	-267	79	x	80
VT1	8	-438	-455	91	x	91
GND	9	-475	-976	91	x	91
NC	10	171	-976	79	x	80
VTEMP	11	475	-976	91	x	91
OUTPUT 2	12	437	-455	91	x	91
NC	13	479	-288	79	x	80
NC	14	479	-126	79	x	80
NC	15	479	36	79	x	80
NC	16	479	198	79	x	80
OUTPUT 1	17	475	366	91	x	91
NC	18	479	615	79	x	80
NC	19	479	778	79	x	80
V+	20	475	976	91	x	91

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